



Product Change Notification / RMES-20UKIQ053

Date:

10-Sep-2021

Product Category:

8-bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4410 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected products available in 64L LQFP (10x10x1.4mm) package using 236 x 236 mils lead frame paddle size at ANAP assembly site.

Affected CPNs:

[RMES-20UKIQ053_Affected_CPN_09102021.pdf](#)
[RMES-20UKIQ053_Affected_CPN_09102021.csv](#)

Notification Text:**PCN Status:**

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected products available in 64L LQFP (10x10x1.4mm) package using 236 x 236 mils lead frame paddle size at ANAP assembly site.

Pre Change:

Using palladium copper bond wire (CuPd) **or** palladium gold (AuPd) with 236 x 236 mils **or** 197 x 197 mils paddle size

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire with 236 x 236 mils paddle size

Pre and Post Change Summary:

		Pre Change	Post Change
Assembly Site		Amkor Technology Philippine (P1/P2), INC. (ANAP)	Amkor Technology Philippine (P1/P2), INC. (ANAP)
Bond wire material		CuPd or AuPd	CuPdAu
Die attach material		3230	3230
Mold compound material		G700	G700
Lead frame	Material	C194	C194
	Paddle size	236 x 236 mils or 197 x 197 mils	236 x 236 mils
	DAP Surface Prep	Double Ring Ag or Ring Ag	Double Ring Ag
	Design	Please see attached pre and post change summary	

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire using 236 x 236 mils lead frame paddle size at ANAP assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

September 30, 2021 (date code: 2140)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	October 2020					>	September 2021				
	40	41	42	43	44		36	37	38	39	40
Initial PCN Issue Date				X							
Qual Report Availability							X				
Final PCN Issue Date							X				
Estimated Implementation Date											X

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

October 21, 2020: Issued initial notification.

September 10, 2021: Issued final notification. Added the lead frame design and DAP Surface Prep. Attached the Qualification Report and Pre Post Change Summary. Provided estimated first ship date to be on September 30, 2021.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_RMES-20UKIQ053_Qual_Report.pdf](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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